

September 2000 Revised June 2005

#### 74LCXZ162244

## Low Voltage 16-Bit Buffer/Line Driver with 5V Tolerant Inputs/Outputs and 26 $\Omega$ Series Resistors in the Outputs

#### **General Description**

The LCXZ162244 contains sixteen non-inverting buffers with 3-STATE outputs designed to be employed as a memory and address driver, clock driver, or bus oriented transmitter/receiver. The device is nibble controlled. Each nibble has separate 3-STATE control inputs which can be shorted together for full 16-bit operation.

When  $V_{CC}$  is between 0 and 1.5V, the LCXZ162244 is in the high impedance state during power up or power down. this places the outputs in the high impedance (Z) state preventing intermittent low impedance loading or glitching in bus oriented applications.

The LCXZ162244 is designed for low voltage (2.7V or 3.3V)  $\rm V_{CC}$  applications with capability of interfacing to a 5V signal environment.

In addition the outputs include  $26\Omega$  (nominal) series resistors to reduce overshoot and undershoot and are designed to sink/source 12 mA at  $V_{CC}=3.0V.$ 

The LCXZ162244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

#### **Features**

- 5V tolerant inputs and outputs
- Guaranteed power up/down high impedance
- Supports live insertion/withdrawal
- $\blacksquare$  Outputs have equivalent 26 $\Omega$  series resistors
- 2.7V-3.6V V<sub>CC</sub> specifications provided
- 5.3 ns  $t_{PD}$  max ( $V_{CC}$  = 3.0V), 20  $\mu$ A  $I_{CC}$  max
- $\pm$ 12 mA output drive ( $V_{CC} = 3.0V$ )
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V Machine model > 200V

#### **Ordering Code:**

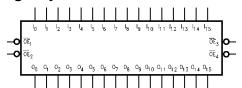
Order Number	Package Number	Package Description	
74LCXZ162244MEA	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide [TUBES]	
74LCXZ162244MEX (Note 1)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide [TAPE and REEL]	
74LCXZ162244MTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide [TUBES]	
74LCXZ162244MTX (Note 1)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide [TAPE and REEL]	

Note 1: Use this Order Number to receive devices in Tape and Reel.

#### **Connection Diagram**



#### **Logic Symbol**



#### **Pin Descriptions**

Pin Names	Description		
$\overline{OE}_n$	Output Enable Input (Active LOW)		
I <sub>0</sub> -I <sub>15</sub>	Inputs		
O <sub>0</sub> -O <sub>15</sub>	Outputs		

#### **Truth Tables**

Inputs		Outputs
OE <sub>1</sub>	I <sub>0</sub> -I <sub>3</sub>	O <sub>0</sub> -O <sub>3</sub>
L	L	L
L	Н	Н
Н	Х	Z

Inp	Outputs	
OE <sub>3</sub> I <sub>8</sub> -I <sub>11</sub>		O <sub>8</sub> -O <sub>11</sub>
L	L	L
L	Н	Н
Н	X	Z

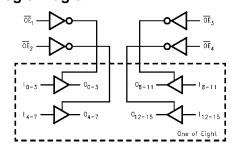
Inputs		Outputs
OE <sub>2</sub>	I <sub>4</sub> –I <sub>7</sub>	O <sub>4</sub> -O <sub>7</sub>
L	L	L
L	Н	Н
Н	Х	Z

Inp	Outputs	
OE <sub>4</sub> I <sub>12</sub> -I <sub>15</sub>		O <sub>12</sub> -O <sub>15</sub>
L	L	L
L	Н	Н
Н	Х	Z

#### **Functional Description**

The LCXZ162244 contains sixteen non-inverting buffers with 3-STATE standard outputs. The device is nibble (4 bits) controlled with each nibble functioning identically, but independent of the other. The control pins can be shorted together to obtain full 16-bit operation. The 3-STATE outputs are controlled by an Output Enable  $(\overline{OE}_n)$ input for each nibble. When  $\overline{OE}_n$  is LOW, the outputs are in 2-state mode. When  $\overline{\text{OE}}_{\text{n}}$  is HIGH, the outputs are in the high impedance mode, but this does not interfere with entering new data into the inputs.

#### **Logic Diagram**



H = HIGH Voltage Level L = LOW Voltage Level

X = Immaterial
Z = High Impedance

°C

#### Absolute Maximum Ratings(Note 2) Parameter Units Symbol Value Conditions ٧ -0.5 to +7.0 Supply Voltage $V_{CC}$ ٧ DC Input Voltage -0.5 to +7.0 $V_{I}$ ٧o DC Output Voltage -0.5 to +7.0 Output in 3-STATE or $V_{CC} = 0-1.5V$ ٧ -0.5 to $V_{CC} + 0.5$ Output in HIGH or LOW State (Note 3) DC Input Diode Current -50 V<sub>I</sub> < GND mΑ $I_{\mathsf{IK}}$ DC Output Diode Current -50 V<sub>O</sub> < GND IOK mΑ +50 $V_O > V_{CC}$ DC Output Source/Sink Current ±50 mΑ $I_{O}$ $I_{CC}$ DC Supply Current per Supply Pin ±100 mΑ DC Ground Current per Ground Pin ±100 $I_{GND}$

-65 to +150

#### **Recommended Operating Conditions** (Note 4)

Symbol	Parameter			Max	Units
V <sub>CC</sub>	Supply Voltage	Operating	2.7	3.6	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	HIGH or LOW State	0	V <sub>CC</sub>	V
		3-STATE	0	5.5	v
I <sub>OH</sub> /I <sub>OL</sub>	Output Current	$V_{CC} = 3.0V - 3.6V$ $V_{CC} = 2.7V - 3.0V$		±12	mA
		$V_{CC} = 2.7V - 3.0V$		±8	IIIA
T <sub>A</sub>	Free-Air Operating Temperature		-40	85	°C
Δt/ΔV	Input Edge Rate, V <sub>IN</sub> = 0.8V–2.0V, V <sub>CC</sub> = 3.0V		0	10	ns/V

Note 2: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 3: I<sub>O</sub> Absolute Maximum Rating must be observed.

Storage Temperature

 $T_{STG}$ 

Note 4: Unused inputs must be held HIGH or LOW. They may not float.

#### **DC Electrical Characteristics**

Symbol	Parameter	Conditions	V <sub>CC</sub>	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Units
Symbol		Conditions	(V)	Min	Max	Units
V <sub>IH</sub>	HIGH Level Input Voltage		2.7 – 3.6	2.0		V
V <sub>IL</sub>	LOW Level Input Voltage		2.7 – 3.6		0.8	V
V <sub>OH</sub>	HIGH Level Output Voltage	I <sub>OH</sub> = -100 μA	2.7 – 3.6	V <sub>CC</sub> - 0.2		
		I <sub>OH</sub> = -4 mA	2.7	2.2		
		I <sub>OH</sub> = -6 mA	3.0	2.4		V
		I <sub>OH</sub> = -8 mA	2.7			
		I <sub>OH</sub> = -12 mA	3.0	2.0		
V <sub>OL</sub>	LOW Level Output Voltage	I <sub>OL</sub> = 100 μA	2.7 - 3.6		0.2	
		I <sub>OL</sub> = 4 mA	2.7		0.4	
		I <sub>OL</sub> = 6 mA	3.0		0.55	V
		I <sub>OL</sub> = 8 mA	2.7		0.6	
		I <sub>OL</sub> = 12 mA	3.0		0.8	
I <sub>I</sub>	Input Leakage Current	$0 \leq V_I \leq 5.5V$	2.7 - 3.6		±5.0	μΑ
l <sub>OZ</sub>	3-STATE Output Leakage	$0 \le V_O \le 5.5V$	2.7 - 3.6		±5.0	
		$V_I = V_{IH}$ or $V_{IL}$	2.7 - 3.0	2.7 - 3.0		μА
I <sub>OFF</sub>	Power-Off Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 5.5V	0		10	μА
I <sub>PU/PD</sub>	Power Up/Down	$V_O = 0.5V$ to $V_{CC}$	0 – 1.5		±5.0	۸
	3-STATE Output Current	$V_I = GND \text{ or } V_{CC}$	0 - 1.5		±5.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>I</sub> = V <sub>CC</sub> or GND	2.7 - 3.6		225	
		$3.6V \le V_I, V_O \le 5.5V \text{ (Note 5)}$	2.7 - 3.6		±225	μА
Δlcc	Increase in I <sub>CC</sub> per Input	V <sub>IH</sub> = V <sub>CC</sub> -0.6V	2.7 - 3.6		500	μΑ

## $\begin{tabular}{ll} \textbf{DC Electrical Characteristics} & (Continued) \\ \textbf{Note 5: Outputs disabled or 3-STATE only.} \\ \end{tabular}$

### **AC Electrical Characteristics**

		$T_A = -40^{\circ}\text{C to} + 85^{\circ}\text{C}, R_L = 500 \Omega$				
Symbol	Parameter		$V_{CC}=3.3V\pm0.3V$		V <sub>CC</sub> = 2.7V	
Syllibol	Farameter	C <sub>L</sub> =	50 pF	C <sub>L</sub> =	50 pF	Units
		Min	Max	Min	Max	
t <sub>PHL</sub>	Propagation Delay	1.0	5.3	1.0	6.0	ns
t <sub>PLH</sub>	Data to Output	1.0	5.3	1.0	6.0	115
t <sub>PZL</sub>	Output Enable Time	1.0	6.3	1.0	7.1	no
t <sub>PZH</sub>		1.0	6.3	1.0	7.1	ns
t <sub>PLZ</sub>	Output Disable Time	1.0	5.4	1.0	5.7	ns
t <sub>PHZ</sub>		1.0	5.4	1.0	5.7	115
toshl	Output to Output Skew (Note 6)		1.0			ns
toslh			1.0			113

Note 6: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>). Parameter guaranteed by design.

#### **Dynamic Switching Characteristics**

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C	Units
V <sub>OLP</sub>	Quiet Output Dynamic Peak V <sub>OL</sub>	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	0.8	V
V <sub>OLV</sub>	Quiet Output Dynamic Valley V <sub>OL</sub>	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	-0.8	V

### Capacitance

Symbol	Parameter	Conditions	Typical	Units
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = Open, V <sub>I</sub> = 0V or V <sub>CC</sub>	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.3V$ , $V_I = 0V$ or $V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	$V_{CC} = 3.3V$ , $V_{I} = 0V$ or $V_{CC}$ , $f = 10$ MHz	20	pF

#### AC LOADING and WAVEFORMS Generic for LCX Family

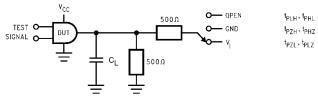
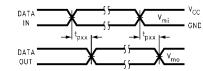
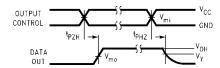


FIGURE 1. AC Test Circuit ( $C_L$  includes probe and jig capacitance)

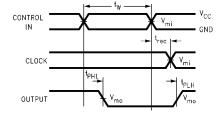
V <sub>I</sub>	CL
6V for V <sub>CC</sub> = 3.3V, 2.7V	50 pF
$V_{CC}$ * 2 for $V_{CC}$ = 2.5V	30 pF



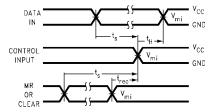
**Waveform for Inverting and Non-Inverting Functions** 



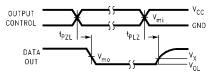
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and  $\mathbf{t}_{\text{rec}}$  Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

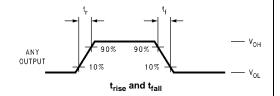
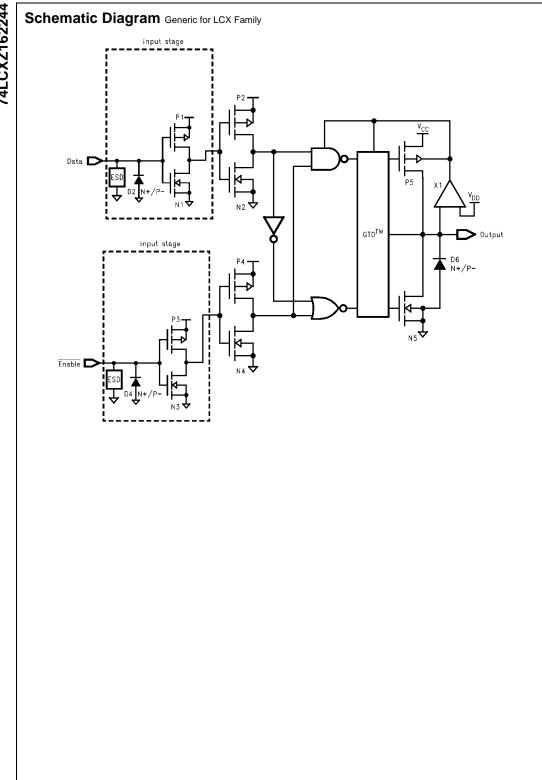
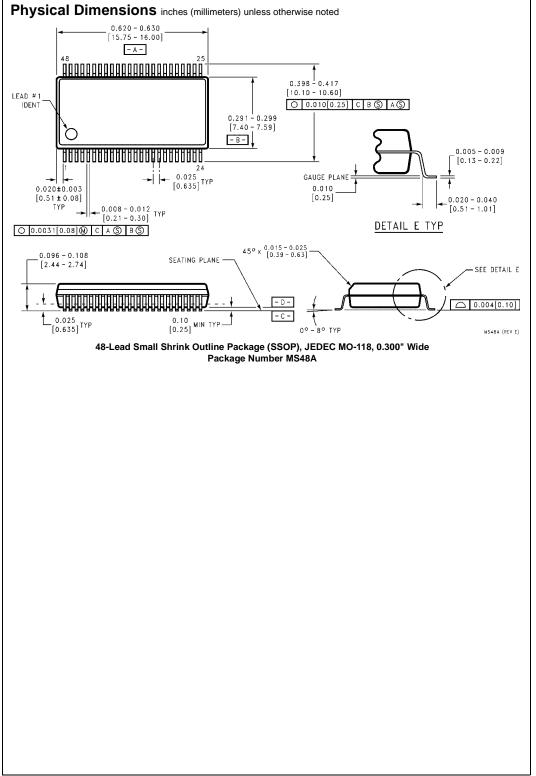


FIGURE 2. Waveforms (Input Characteristics; f =1MHz,  $t_R = t_F = 3ns$ )

Symbol	V <sub>cc</sub>	
	3.3V ± 0.3V	2.7V
V <sub>mi</sub>	1.5V	1.5V
$V_{mo}$	1.5V	1.5V
V <sub>x</sub>	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.3V
V <sub>y</sub>	V <sub>OH</sub> – 0.3V	V <sub>OH</sub> – 0.3V





# in the Outputs

#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-99. 9.20 8.10 59. O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION 0.1 C SEE DETAIL A 0.90+0.15 0.09-0.20 0.10±0.05 0.17-0.27 0.50 ♦ 0.13@ A BS CS 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 1.00 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com